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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	64MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	35
Program Memory Size	8KB (4K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 30x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f43k22-i-pt

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1.0 DEVICE OVERVIEW

This document contains device specific information for the following devices:

- PIC18F23K22 PIC18LF23K22
- PIC18F24K22 PIC18LF24K22
- PIC18F25K22
 PIC18LF25K22
- PIC18F26K22 PIC18LF26K22
- PIC18F43K22 PIC18LF43K22
- PIC18F44K22 PIC18LF44K22
- PIC18F45K22 PIC18LF45K22
- PIC18F46K22 PIC18LF46K22

This family offers the advantages of all PIC18 microcontrollers – namely, high computational performance at an economical price – with the addition of high-endurance, Flash program memory. On top of these features, the PIC18(L)F2X/4XK22 family introduces design enhancements that make these microcontrollers a logical choice for many high-performance, power sensitive applications.

1.1 New Core Features

1.1.1 XLP TECHNOLOGY

All of the devices in the PIC18(L)F2X/4XK22 family incorporate a range of features that can significantly reduce power consumption during operation. Key items include:

- Alternate Run Modes: By clocking the controller from the Timer1 source or the internal oscillator block, power consumption during code execution can be reduced by as much as 90%.
- Multiple Idle Modes: The controller can also run with its CPU core disabled but the peripherals still active. In these states, power consumption can be reduced even further, to as little as 4% of normal operation requirements.
- **On-the-fly Mode Switching:** The powermanaged modes are invoked by user code during operation, allowing the user to incorporate powersaving ideas into their application's software design.
- Low Consumption in Key Modules: The power requirements for both Timer1 and the Watchdog Timer are minimized. See Section 27.0 "Electrical Specifications" for values.

1.1.2 MULTIPLE OSCILLATOR OPTIONS AND FEATURES

All of the devices in the PIC18(L)F2X/4XK22 family offer ten different oscillator options, allowing users a wide range of choices in developing application hardware. These include:

- Four Crystal modes, using crystals or ceramic resonators
- Two External Clock modes, offering the option of using two pins (oscillator input and a divide-by-4 clock output) or one pin (oscillator input, with the second pin reassigned as general I/O)
- Two External RC Oscillator modes with the same pin options as the External Clock modes
- An internal oscillator block which contains a 16 MHz HFINTOSC oscillator and a 31 kHz LFINTOSC oscillator, which together provide eight user selectable clock frequencies, from 31 kHz to 16 MHz. This option frees the two oscillator pins for use as additional general purpose I/O.
- A Phase Lock Loop (PLL) frequency multiplier, available to both external and internal oscillator modes, which allows clock speeds of up to 64 MHz. Used with the internal oscillator, the PLL gives users a complete selection of clock speeds, from 31 kHz to 64 MHz – all without using an external crystal or clock circuit.

Besides its availability as a clock source, the internal oscillator block provides a stable reference source that gives the family additional features for robust operation:

- Fail-Safe Clock Monitor: This option constantly monitors the main clock source against a reference signal provided by the LFINTOSC. If a clock failure occurs, the controller is switched to the internal oscillator block, allowing for continued operation or a safe application shutdown.
- **Two-Speed Start-up:** This option allows the internal oscillator to serve as the clock source from Power-on Reset, or Wake-up from Sleep mode, until the primary clock source is available.

TABLE 4-2: TIME-OUT IN VARIOUS SITUATIONS

Oscillator	Power-up ⁽²⁾ a	Exit from	
Configuration	PWRTEN = 0	PWRTEN = 1	Power-Managed Mode
HSPLL	66 ms ⁽¹⁾ + 1024 Tosc + 2 ms ⁽²⁾	1024 Tosc + 2 ms ⁽²⁾	1024 Tosc + 2 ms ⁽²⁾
HS, XT, LP	66 ms ⁽¹⁾ + 1024 Tosc	1024 Tosc	1024 Tosc
EC, ECIO	66 ms ⁽¹⁾	_	—
RC, RCIO	66 ms ⁽¹⁾	_	—
INTIO1, INTIO2	66 ms ⁽¹⁾	_	—

Note 1: 66 ms (65.5 ms) is the nominal Power-up Timer (PWRT) delay.2: 2 ms is the nominal time required for the PLL to lock.

FIGURE 4-3: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD, VDD RISE < TPWRT)



FIGURE 4-4: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 1



5.0 MEMORY ORGANIZATION

There are three types of memory in PIC18 Enhanced microcontroller devices:

- Program Memory
- Data RAM
- Data EEPROM

As Harvard architecture devices, the data and program memories use separate buses; this allows for concurrent access of the two memory spaces. The data EEPROM, for practical purposes, can be regarded as a peripheral device, since it is addressed and accessed through a set of control registers.

Additional detailed information on the operation of the Flash program memory is provided in **Section 6.0 "Flash Program Memory"**. Data EEPROM is discussed separately in **Section 7.0 "Data EEPROM Memory"**.

5.1 Program Memory Organization

PIC18 microcontrollers implement a 21-bit program counter, which is capable of addressing a 2-Mbyte program memory space. Accessing a location between the upper boundary of the physically implemented memory and the 2-Mbyte address will return all '0's (a NOP instruction).

This family of devices contain the following:

- PIC18(L)F23K22, PIC18(L)F43K22: 8 Kbytes of Flash Memory, up to 4,096 single-word instructions
- PIC18(L)F24K22, PIC18(L)F44K22: 16 Kbytes of Flash Memory, up to 8,192 single-word instructions
- PIC18(L)F25K22, PIC18(L)F45K22: 32 Kbytes of Flash Memory, up to 16,384 single-word instructions
- PIC18(L)F26K22, PIC18(L)F46K22: 64 Kbytes of Flash Memory, up to 37,768 single-word instructions

PIC18 devices have two interrupt vectors. The Reset vector address is at 0000h and the interrupt vector addresses are at 0008h and 0018h.

The program memory map for PIC18(L)F2X/4XK22 devices is shown in Figure 5-1. Memory block details are shown in Figure 20-2.

PIC18(L)F2X/4XK22

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	<u>Value on</u> POR, BOR
FD1h	WDTCON	_	_	_	_	_	_	_	SWDTEN	0
FD0h	RCON	IPEN	SBOREN	_	RI	TO	PD	POR	BOR	01-1 1100
FCFh	TMR1H		Holding R	egister for the	Most Significa	ant Byte of the	16-bit TMR1 R	egister		xxxx xxxx
FCEh	TMR1L			Least Signifi	icant Byte of th	e 16-bit TMR1	Register			xxxx xxxx
FCDh	T1CON	TMR1C	S<1:0>	T1CKF	PS<1:0>	T1SOSCEN	T1SYNC	T1RD16	TMR10N	0000 0000
FCCh	T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T <u>1GGO</u> / DONE	T1GVAL	T1GSS	S<1:0>	0000 xx00
FCBh	SSP1CON3	ACKTIM	PCIE	SCIE	BOEN	SDAHT	SBCDE	AHEN	DHEN	0000 0000
FCAh	SSP1MSK			:	SSP1 MASK R	legister bits				1111 1111
FC9h	SSP1BUF			SSP1	Receive Buffer	/Transmit Reg	ister			XXXX XXXX
FC8h	SSP1ADD	SSP1 /	Address Regis	ster in I ² C Slav	ve Mode. SSP	1 Baud Rate R	eload Register	in I ² C Master	Mode	0000 0000
FC7h	SSP1STAT	SMP	CKE	D/A	Р	S	R/W	UA	BF	0000 0000
FC6h	SSP1CON1	WCOL	SSPOV	SSPEN	CKP		SSPM	<3:0>		0000 0000
FC5h	SSP1CON2	GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	0000 0000
FC4h	ADRESH				A/D Result,	High Byte				XXXX XXXX
FC3h	ADRESL				A/D Result,	Low Byte		-	-	xxxx xxxx
FC2h	ADCON0	_			CHS<4:0>	-		GO/DONE	ADON	00 0000
FC1h	ADCON1	TRIGSEL	_	_	_	PVCF	G<1:0>	NVCF	G<1:0>	0 0000
FC0h	ADCON2	ADFM	-		ACQT<2:0>			ADCS<2:0>		0-00 0000
FBFh	CCPR1H			Captur	e/Compare/PV	VM Register 1,	High Byte			xxxx xxxx
FBEh	CCPR1L			Captur	e/Compare/PV	VM Register 1,	Low Byte			xxxx xxxx
FBDh	CCP1CON	P1M<	:1:0>	DC1E	8<1:0>		CCP1N	l<3:0>		0000 0000
FBCh	TMR2				Timer2 F	Register				0000 0000
FBBh	PR2				Timer2 Peri	od Register		-		1111 1111
FBAh	T2CON	_		T2OUT	PS<3:0>	-	TMR2ON	T2CKP	S<1:0>	-000 0000
FB9h	PSTR1CON	_	-	-	STR1SYNC	STR1D	STR1C	STR1B	STR1A	0 0001
FB8h	BAUDCON1	ABDOVF	RCIDL	DTRXP	CKTXP	BRG16	-	WUE	ABDEN	0100 0-00
FB7h	PWM1CON	P1RSEN				P1DC<6:0>				0000 0000
FB6h	ECCP1AS	CCP1ASE		CCP1AS<2:0:	>	PSS1A	C<1:0>	PSS1B	D<1:0>	0000 0000
FB4h	T3GCON	TMR3GE	T3GPOL	T3GTM	T3GSPM	T <u>3GGO</u> / DONE	T3GVAL	T3GSS	S<1:0>	00x0 0x00
FB3h	TMR3H		Holding R	egister for the	Most Significa	ant Byte of the	16-bit TMR3 R	egister		xxxx xxxx
FB2h	TMR3L			Least Signifi	cant Byte of th	e 16-bit TMR3	Register	n	r	xxxx xxxx
FB1h	T3CON	TMR3C	S<1:0>	T3CKF	°S<1:0>	T3SOSCEN	T3SYNC	T3RD16	TMR3ON	0000 0000
FB0h	SPBRGH1			EUSAR	T1 Baud Rate	Generator, Hig	h Byte			0000 0000
FAFh	SPBRG1			EUSAR	T1 Baud Rate	Generator, Lov	w Byte			0000 0000
FAEh	RCREG1			EUSAR	T1 Receive Re	egister				0000 0000
FADh	TXREG1			EUSAR	T1 Transmit R	egister		r	r	0000 0000
FACh	TXSTA1	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	0000 0010
FABh	RCSTA1	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x
FAAh	EEADRH ⁽⁵⁾	_	_	_	_	_	_	EEAD	R<9:8>	00
FA9h	EEADR				EEAD	R<7:0>				0000 0000
FA8h	EEDATA				EEPROM Da	ita Register				0000 0000
FA7h	EECON2			EEPROM Co	ontrol Register	2 (not a physic	cal register)	1	1	00
FA6h	EECON1	EEPGD	CFGS	_	FREE	WRERR	WREN	WR	RD	xx-0 x000
FA5h	IPR3	SSP2IP	BCL2IP	RC2IP	TX2IP	CTMUIP	TMR5GIP	TMR3GIP	TMR1GIP	0000 0000
FA4h	PIR3	SSP2IF	BCL2IF	RC2IF	TX2IF	CTMUIF	TMR5GIF	TMR3GIF	TMR1GIF	0000 0000
FA3h	PIE3	SSP2IE	BCL2IE	RC2IE	TX2IE	CTMUIE	TMR5GIE	TMR3GIE	TMR1GIE	0000 0000

TABLE 5-2: REGISTER FILE SUMMARY FOR PIC18(L)F2X/4XK22 DEVICES (CONTINUED)

Legend: \mathbf{x} = unknown, \mathbf{u} = unchanged, — = unimplemented, \mathbf{q} = value depends on condition

PIC18(L)F4XK22 devices only. Note 1:

PIC18(L)F2XK22 devices only. 2:

PIC18(L)F23/24K22 and PIC18(L)F43/44K22 devices only. PIC18(L)F26K22 and PIC18(L)F46K22 devices only. 3:

4:

DS40001412G-page 80

	-		-		· / -	-	
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SSP2IE	BCL2IE	RC2IE	TX2IE	CTMUIE	TMR5GIE	TMR3GIE	TMR1GIE
bit 7							bit 0
Legend:							
R = Readable	e bit	W = Writable	bit	U = Unimpler	mented bit, read	d as '0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown
bit 7	SSP2IF: Mas	ter Synchrono	us Serial Port	2 Interrupt Ena	able bit		
2	1 = Enables	the MSSP2 int	errupt	op:			
	0 = Disables	the MSSP2 in	terrupt				
bit 6	BCL2IE: Bus	Collision Inter	rupt Enable b	it			
	1 = Enabled						
	0 = Disabled						
bit 5	RC2IE: EUSA	ART2 Receive	Interrupt Enal	ole bit			
	1 = Enabled						
h:+ 4			latera vet En el	hla hit			
DIT 4	1 AZIE: EUSA	ARIZ Transmit	Interrupt Ena	DIE DIT			
	1 = Disabled 0 = Disabled						
bit 3	CTMUIE: CT	MU Interrupt E	nable bit				
	1 = Enabled	•					
	0 = Disabled						
bit 2	TMR5GIE: T	MR5 Gate Inter	rupt Enable b	bit			
	1 = Enabled						
	0 = Disabled						
bit 1	TMR3GIE: T	MR3 Gate Inter	rupt Enable b	bit			
	1 = Enabled						
hit 0		MP1 Cate Inter	runt Enable h	t			
	1 = Fnabled			//1			
	0 = Disabled						

REGISTER 9-11: PIE3: PERIPHERAL INTERRUPT ENABLE (FLAG) REGISTER 3

TABLE 10-8: PORTC I/O SUMMARY

Pin Name	Function	TRIS Setting	ANSEL setting	Pin Type	Buffer Type	Description
RC0/P2B/T3CKI/T3G/	RC0	0	—	0	DIG	LATC<0> data output; not affected by analog input.
T1CKI/SOSCO		1	PORTC<0> data input; disabled when analog input enabled.			
	P2B ⁽²⁾	0	—	0	DIG	Enhanced CCP2 PWM output 2.
	T3CKI ⁽¹⁾	1	_	Ι	ST	Timer3 clock input.
	T3G	1	_	Ι	ST	Timer3 external clock gate input.
	T1CKI	1	_	I	ST	Timer1 clock input.
	SOSCO	х	_	0	XTAL	Secondary oscillator output.
RC1/P2A/CCP2/SOSCI	RC1	0	_	0	DIG	LATC<1> data output; not affected by analog input.
		1	—	Ι	ST	PORTC<1> data input; disabled when analog input enabled.
	P2A	0	_	0	DIG	Enhanced CCP2 PWM output 1.
	CCP2 ⁽¹⁾	0	_	0	DIG	Compare 2 output/PWM 2 output.
		1	_	Ι	ST	Capture 2 input.
	SOSCI	х	_	Ι	XTAL	Secondary oscillator input.
RC2/CTPLS/P1A/	RC2	0	0	0	DIG	LATC<2> data output; not affected by analog input.
CCP1/T5CKI/AN14		1	0	Ι	ST	PORTC<2> data input; disabled when analog input enabled.
	CTPLS	0	0	0	DIG	CTMU pulse generator output.
	P1A	0	0	0	DIG	Enhanced CCP1 PWM output 1.
	CCP1	0	0	0	DIG	Compare 1 output/PWM 1 output.
		1	0	I	ST	Capture 1 input.
	T5CKI	1	0	Ι	ST	Timer5 clock input.
	AN14	1	1	Ι	AN	Analog input 14.
RC3/SCK1/SCL1/AN15	RC3	0	0	0	DIG	LATC<3> data output; not affected by analog input.
		1	0	Ι	ST	PORTC<3> data input; disabled when analog input enabled.
	SCK1	0	0	0	DIG	MSSP1 SPI Clock output.
		1	0	Ι	ST	MSSP1 SPI Clock input.
	SCL1	0	0	0	DIG	MSSP1 I ² C Clock output.
		1	0	I	l ² C	MSSP1 I ² C Clock input.
	AN15	1	1	Ι	AN	Analog input 15.
RC4/SDI1/SDA1/AN16	RC4	0	0	0	DIG	LATC<4> data output; not affected by analog input.
		1	0	Ι	ST	PORTC<4> data input; disabled when analog input enabled.
	SDI1	1	0	I	ST	MSSP1 SPI data input.
	SDA1	0	0	0	DIG	MSSP1 I ² C data output.
		1	0	I	I ² C	MSSP1 I ² C data input.
	AN16	1	1	I	AN	Analog input 16.

Legend: AN = Analog input or output; TTL = TTL compatible input; $HV = High Voltage; OD = Open Drain; XTAL = Crystal; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; <math>I^2C$ = Schmitt Trigger input with I^2C .

Note 1: Default pin assignment for P2B, T3CKI, CCP3 and CCP2 when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are set.

2: Alternate pin assignment for P2B, T3CKI, CCP3 and CCP2 when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are clear.

3: Function on PORTD and PORTE for PIC18(L)F4XK22 devices.

TIMER1/3/5 MODULE WITH 12.0 GATE CONTROL

The Timer1/3/5 module is a 16-bit timer/counter with the following features:

- 16-bit timer/counter register pair (TMRxH:TMRxL)
- · Programmable internal or external clock source
- 2-bit prescaler ٠
- Dedicated Secondary 32 kHz oscillator circuit
- · Optionally synchronized comparator out
- Multiple Timer1/3/5 gate (count enable) sources ٠
- Interrupt on overflow
- · Wake-up on overflow (external clock, Asynchronous mode only)
- 16-Bit Read/Write Operation
- Time base for the Capture/Compare function
- module.

TIMER1/3/5 BLOCK DIAGRAM TxGSS<1:0> TxGSPM TxG 🗙 00 Timer2/4/6 Match 01 TxG_IN 0 Data Bus PR2/4/6 TxGVAL C Single Pulse RD sync_C1OUT(7) 10 XGCON ΕN Q1 Acq. Control Q D 11 sync_C2OUT(7) Interrupt TxGGO/DONE Set C CK **TMRxON** TMRxGIF det R TXGTM TxGPOL TMRxGE Set flag bit TMRxON TMRxIF on To Comparator Module Overflow TMRx^{(2),(4)} ΕN Synchronized clock input TMRxH TxCLK TMRxL Г TMRxCS<1:0> Secondary TXSYNC SOSCOUT Oscillator Module Reserved See Figure 2-4 11 Synchronize(3),(7) Prescaler 1, 2, 4, 8 det TxCLK EXT SRC 10 (5),(6) (1) ₹ 2 тхскі 🛛 TxCKPS<1:0> Fosc 01 Internal Clock Fosc/2 TxSOSCEN Sleep input Internal Fosc/4 Clock 00 Internal Clock Note 1: ST Buffer is high speed type when using TxCKI. 2: Timer1/3/5 register increments on rising edge. Synchronize does not operate while in Sleep. 3: 4: See Figure 12-2 for 16-Bit Read/Write Mode Block Diagram. T1CKI is not available when the secondary oscillator is enabled. (SOSCGO = 1 or TXSOSCEN = 1) 5: 6: T3CKI is not available when the secondary oscillator is enabled, unless T3CMX = 1. 7: Synchronized comparator output should not be used in conjunction with synchronized TxCKI.

FIGURE 12-1:

- Special Event Trigger (with CCP/ECCP)
- · Selectable Gate Source Polarity
- Gate Toggle mode
- · Gate Single-pulse mode
- Gate Value Status
- Gate Event Interrupt

Figure 12-1 is a block diagram of the Timer1/3/5





14.4.3 ENHANCED PWM AUTO-SHUTDOWN MODE

The PWM mode supports an Auto-Shutdown mode that will disable the PWM outputs when an external shutdown event occurs. Auto-Shutdown mode places the PWM output pins into a predetermined state. This mode is used to help prevent the PWM from damaging the application.

The auto-shutdown sources are selected using the CCPxAS<2:0> bits of the ECCPxAS register. A shutdown event may be generated by:

- A logic '0' on the INT pin
- Comparator Cx (async_CxOUT)
- Setting the CCPxASE bit in firmware

A shutdown condition is indicated by the CCPxASE (Auto-Shutdown Event Status) bit of the ECCPxAS register. If the bit is a '0', the PWM pins are operating normally. If the bit is a '1', the PWM outputs are in the shutdown state.

When a shutdown event occurs, two things happen:

The CCPxASE bit is set to '1'. The CCPxASE will remain set until cleared in firmware or an auto-restart occurs (see Section 14.4.4 "Auto-Restart Mode").

The enabled PWM pins are asynchronously placed in their shutdown states. The PWM output pins are grouped into pairs [PxA/PxC] and [PxB/PxD].

The state of each pin pair is determined by the PSSxAC<1:0> and PSSxBD<1:0> bits of the ECCPxAS register. Each pin pair may be placed into one of three states:

- Drive logic '1'
- Drive logic '0'
- Tri-state (high-impedance)

Note 1: The auto-shutdown condition is a levelbased signal, not an edge-based signal. As long as the level is present, the autoshutdown will persist.

- 2: Writing to the CCPxASE bit is disabled while an auto-shutdown condition persists.
- **3:** Once the auto-shutdown condition has been removed and the PWM restarted (either through firmware or auto-restart), the PWM signal will always restart at the beginning of the next PWM period.



FIGURE 15-19:

PIC18(L)F2X/4XK22

15.6.8 ACKNOWLEDGE SEQUENCE TIMING

An Acknowledge sequence is enabled by setting the Acknowledge Sequence Enable bit, ACKEN, of the SSPxCON2 register. When this bit is set, the SCLx pin is pulled low and the contents of the Acknowledge data bit are presented on the SDAx pin. If the user wishes to generate an Acknowledge, then the ACKDT bit should be cleared. If not, the user should set the ACKDT bit before starting an Acknowledge sequence. The Baud Rate Generator then counts for one rollover period (TBRG) and the SCLx pin is deasserted (pulled high). When the SCLx pin is sampled high (clock arbitration), the Baud Rate Generator counts for TBRG. The SCLx pin is then pulled low. Following this, the ACKEN bit is automatically cleared, the Baud Rate Generator is turned off and the MSSPx module then goes into Idle mode (Figure 15-30).

15.6.8.1 WCOL Status Flag

If the user writes the SSPxBUF when an Acknowledge sequence is in progress, then WCOL is set and the contents of the buffer are unchanged (the write does not occur).

15.6.9 STOP CONDITION TIMING

A Stop bit is asserted on the SDAx pin at the end of a receive/transmit by setting the Stop Sequence Enable bit, PEN, of the SSPxCON2 register. At the end of a receive/transmit, the SCLx line is held low after the falling edge of the ninth clock. When the PEN bit is set, the master will assert the SDAx line low. When the SDAx line is sampled low, the Baud Rate Generator is reloaded and counts down to '0'. When the Baud Rate Generator times out, the SCLx pin will be brought high and one TBRG (Baud Rate Generator rollover count) later, the SDAx pin will be deasserted. When the SDAx pin is sampled high while SCLx is high, the P bit of the SSPxSTAT register is set. A TBRG later, the PEN bit is cleared and the SSPxIF bit is set (Figure 15-31).

15.6.9.1 WCOL Status Flag

If the user writes the SSPxBUF when a Stop sequence is in progress, then the WCOL bit is set and the contents of the buffer are unchanged (the write does not occur).

FIGURE 15-30: ACKNOWLEDGE SEQUENCE WAVEFORM



15.6.13.3 Bus Collision During a Stop Condition

Bus collision occurs during a Stop condition if:

- a) After the SDAx pin has been deasserted and allowed to float high, SDAx is sampled low after the BRG has timed out (Case 1).
- b) After the SCLx pin is deasserted, SCLx is sampled low before SDAx goes high (Case 2).

The Stop condition begins with SDAx asserted low. When SDAx is sampled low, the SCLx pin is allowed to float. When the pin is sampled high (clock arbitration), the Baud Rate Generator is loaded with SSPxADD and counts down to zero. After the BRG times out, SDAx is sampled. If SDAx is sampled low, a bus collision has occurred. This is due to another master attempting to drive a data '0' (Figure 15-38). If the SCLx pin is sampled low before SDAx is allowed to float high, a bus collision occurs. This is another case of another master attempting to drive a data '0' (Figure 15-39).

FIGURE 15-38: BUS COLLISION DURING A STOP CONDITION (CASE 1)



FIGURE 15-39: BUS COLLISION DURING A STOP CONDITION (CASE 2)



16.3 Register Definitions: EUSART Control

REGISTER 16-1: TxSTAx: TRANSMIT STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-1	R/W-0
CSRC	TX9	TXEN ⁽¹⁾	SYNC	SENDB	BRGH	TRMT	TX9D
bit 7		· ·		·			bit 0
Legend:							
R = Readable	e bit	W = Writable bit		U = Unimpleme	ented bit, read as	'0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is clear	red	x = Bit is unknow	wn
bit 7	CSRC: Clock Asynchronous Don't care Synchronous I 1 = Master n 0 = Slave m	Source Select bit <u>s mode</u> : mode: node (clock genera ode (clock from ex	ated internally ternal source)	from BRG)			
bit 6	TX9: 9-bit Train 1 = Selects 8 0 = Selects 8	nsmit Enable bit 9-bit transmission 8-bit transmission	····,				
bit 5	TXEN: Transn 1 = Transmit 0 = Transmit	nit Enable bit ⁽¹⁾ enabled disabled					
bit 4	SYNC: EUSA 1 = Synchror 0 = Asynchror	RT Mode Select bi nous mode pnous mode	t				
bit 3	SENDB: Send Asynchronous 1 = Send Syr 0 = Sync Bre Synchronous I Don't care	Break Character <u>a mode</u> : nc Break on next tr ak transmission co <u>mode</u> :	bit ransmission (c ompleted	cleared by hardwa	are upon completi	on)	
bit 2	BRGH: High E Asynchronous 1 = High spe 0 = Low spee Synchronous Unused in this	Baud Rate Select b <u>s mode</u> : ed ed <u>mode:</u> s mode	bit				
bit 1	TRMT: Transn 1 = TSR emp 0 = TSR full	nit Shift Register S oty	tatus bit				
bit 0	TX9D: Ninth b Can be addres	it of Transmit Data ss/data bit or a par	ı ity bit.				
Note 1: S	REN/CREN overri	des TXEN in Sync	mode.				

18.2 Comparator Control

Each comparator has a separate control and Configuration register: CM1CON0 for Comparator C1 and CM2CON0 for Comparator C2. In addition, Comparator C2 has a second control register, CM2CON1, for controlling the interaction with Timer1 and simultaneous reading of both comparator outputs.

The CM1CON0 and CM2CON0 registers (see Register 18-1) contain the control and status bits for the following:

- Enable
- Input selection
- Reference selection
- Output selection
- Output polarity
- Speed selection

18.2.1 COMPARATOR ENABLE

Setting the CxON bit of the CMxCON0 register enables the comparator for operation. Clearing the CxON bit disables the comparator resulting in minimum current consumption.

18.2.2 COMPARATOR INPUT SELECTION

The CxCH<1:0> bits of the CMxCON0 register direct one of four analog input pins to the comparator inverting input.

Note:	To use CxIN+ and C12INx- pins as analog inputs, the appropriate bits must be set in							
	the ANSEL register and the							
	corresponding TRIS bits must also be set							
	to dis	able the ou	tput drivers.					

18.2.3 COMPARATOR REFERENCE SELECTION

Setting the CxR bit of the CMxCON0 register directs an internal voltage reference or an analog input pin to the non-inverting input of the comparator. See **Section 21.0 "Fixed Voltage Reference (FVR)"** for more information on the Internal Voltage Reference module.

18.2.4 COMPARATOR OUTPUT SELECTION

The output of the comparator can be monitored by reading either the CxOUT bit of the CMxCON0 register or the MCxOUT bit of the CM2CON1 register. In order to make the output available for an external connection, the following conditions must be true:

- CxOE bit of the CMxCON0 register must be set
- · Corresponding TRIS bit must be cleared
- CxON bit of the CMxCON0 register must be set

- Note 1: The CxOE bit overrides the PORT data latch. Setting the CxON has no impact on the port override.
 - 2: The internal output of the comparator is latched with each instruction cycle. Unless otherwise specified, external outputs are not latched.

18.2.5 COMPARATOR OUTPUT POLARITY

Inverting the output of the comparator is functionally equivalent to swapping the comparator inputs. The polarity of the comparator output can be inverted by setting the CxPOL bit of the CMxCON0 register. Clearing the CxPOL bit results in a non-inverted output.

Table 18-1 shows the output state versus input conditions, including polarity control.

TABLE 18-1: COMPARATOR OUTPUT STATE VS. INPUT CONDITIONS

Input Condition	CxPOL	CxOUT
CxVIN - > CxVIN +	0	0
CxVIN- < CxVIN+	0	1
CxVIN - > CxVIN +	1	1
CxVIN- < CxVIN+	1	0

18.2.6 COMPARATOR SPEED SELECTION

The trade-off between speed or power can be optimized during program execution with the CxSP control bit. The default state for this bit is '1' which selects the normal speed mode. Device power consumption can be optimized at the cost of slower comparator propagation delay by clearing the CxSP bit to '0'.

18.3 Comparator Response Time

The comparator output is indeterminate for a period of time after the change of an input source or the selection of a new reference voltage. This period is referred to as the response time. The response time of the comparator differs from the settling time of the voltage reference. Therefore, both of these times must be considered when determining the total response time to a comparator input change. See the Comparator and Voltage Reference Specifications in **Section 27.0 "Electrical Specifications"** for more details.

PIC18(L)F2X/4XK22

CPFSGT Compare f with W, skip if f >							
Synta	ax:	CPFSGT	CPFSGT f {,a}				
Oper	ands:	0 ≤ f ≤ 255 a ∈ [0,1]					
Oper	ation:	(f) – (W), skip if (f) > ((unsigned c	(W) comparison)				
Statu	is Affected:	None					
Enco	oding:	0110	010a fff	f ffff			
Desc	Description: Compares the contents of data memore location 'f' to the contents of the W by performing an unsigned subtraction. If the contents of 'f' are greater than the contents of WREG, then the fetched instruction is discarded and a NOP is executed instruction. If fa' is '0', the Access Bank is selected If 'a' is '1', the BSR is used to select the GPR bank. If 'a' is '0' and the extended instruction operate in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexee Literal Offset Mode" for details.						
Word	ls:	1					
Cycle	es:	1(2) Note: 3 cy by a	1(2) Note: 3 cycles if skip and followed by a 2-word instruction.				
QU	Q1	02	03	Q4			
	Decode	Read	Process	No			
		register 'f'	Data	operation			
lf sk	ip:						
	Q1	Q2	Q3	Q4			
	NO	N0 operation	N0 operation	NO			
lf sk	in and follower	d by 2-word in	struction:	operation			
ii on	Q1	Q2	Q3	Q4			
	No	No	No	No			
	operation	operation	operation	operation			
	No	No	No	No			
	operation	operation	operation	operation			
Example: HERE CPFSGT REG, 0 NGREATER : GREATER :							
	Before Instruc	tion					
	PC	= Ad	dress (HERE)			
	W	= ?					
	After Instruction	n					
	If REG PC	> W; = Ad	dress (GREAT	fer)			

CPFSLT	Compare f with W, skip if f < W					
Syntax:	CPFSLT 1	{,a}				
Operands:	0 ≤ f ≤ 255 a ∈ [0,1]					
Operation:	(f) – (W), skip if (f) < (unsigned c	(W) comparison)				
Status Affected:	None					
Encoding:	0110	000a ffi	ff ffff			
Description:	Compares the contents of data memory location 'f' to the contents of W by performing an unsigned subtraction. If the contents of 'f' are less than the contents of W, then the fetched instruction is discarded and a NOP is executed instead, making this a 2-cycle instruction. If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.					
Words:	1					
Cycles:	1(2) Note: 3 c by	1(2) Note: 3 cycles if skip and followed by a 2-word instruction.				
Q Cycle Activity:						
Q1	Q2	Q3	Q4			
Decode	Read	Process	No			
lf skip:	register i	Data	operation			
Q1	Q2	Q3	Q4			
No	No	No	No			
operation	operation	operation operation				
If skip and followe	d by 2-word in	struction:	_			
Q1	Q2	Q3	Q4			
NO operation	NO operation	NO operation	NO operation			
No	No	No	No			
operation	operation	operation	operation			
Example:	HERE (NLESS LESS	CPFSLT REG, :	1			
Before Instruc	ction					
PC	= Ad	dress (HERE)			
After Instructi	on - :					
If REG	< W;					
PC	= Ad	dress (LESS)			
If REG	≥ W;	≥ W;				
PC	= Ad	UIESS (NLES:	5)			

If REG

PC

≤ W;

= Address (NGREATER)

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
50	TccL	CCPx Input Low	No prescaler	0.5 TCY + 20	—	ns	
		Time	With prescaler	10	—	ns	
51	TccH	CCPx Input	No prescaler	0.5 Tcy + 20	—	ns	
		High Time	With prescaler	10	—	ns	
52	TccP	CCPx Input Period		<u>3 Tcy + 40</u> N	_	ns	N = prescale value (1, 4 or 16)
53	TccR	CCPx Output Fall Time		—	25	ns	
54	TccF	CCPx Output Fa	ll Time	—	25	ns	

TABLE 27-13: CAPTURE/COMPARE/PWM REQUIREMENTS (ALL CCP MODULES)

Param. No.	Symbol	Charact	eristic	Min	Max	Units	Conditions
100	Тнідн	Clock High Time	100 kHz mode	4.0		μS	Must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	_	μS	Must operate at a minimum of 10 MHz
			SSP Module	1.5 TCY	_		
101	TLOW	Clock Low Time	100 kHz mode	4.7	_	μS	Must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3		μS	Must operate at a minimum of 10 MHz
			SSP Module	1.5 TCY	_		
102	TR	SDA and SCL Rise	100 kHz mode	—	1000	ns	
		Time	400 kHz mode	20 + 0.1 Св	300	ns	CB is specified to be from 10 to 400 pF
103	03 TF \$	SDA and SCL Fall	100 kHz mode	—	300	ns	
		Time	400 kHz mode	20 + 0.1 Св	300	ns	CB is specified to be from 10 to 400 pF
90	TSU:STA	Start Condition	100 kHz mode	4.7	—	μS	Only relevant for Repeated
		Setup Time	400 kHz mode	0.6	—	μS	Start condition
91	THD:STA	Start Condition	100 kHz mode	4.0	—	μS	After this period, the first
		Hold Time	400 kHz mode	0.6	—	μS	clock pulse is generated
106	THD:DA	Data Input Hold	100 kHz mode	0	_	ns	
	Т	Time	400 kHz mode	0	0.9	μS	
107	TSU:DAT	Data Input Setup	100 kHz mode	250	_	ns	(Note 2)
		Time	400 kHz mode	100	_	ns	
92	TSU:STO	Stop Condition	100 kHz mode	4.7	—	μS	
		Setup Time	400 kHz mode	0.6	—	μS	
109	ΤΑΑ	Output Valid from	100 kHz mode	—	3500	ns	(Note 1)
		Clock	400 kHz mode	—	—	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	μS	Time the bus must be free
			400 kHz mode	1.3	_	μS	before a new transmission can start
D102	Св	Bus Capacitive Load	ding	—	400	pF	

TABLE 27-16:	I ² C BUS DATA	REQUIREMENTS	(SLAVE MODE)
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Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

2: A fast mode I²C bus device can be used in a standard mode I²C bus system but the requirement, TSU:DAT ≥ 250 ns, must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line, TR max. + TSU:DAT = 1000 + 250 = 1250 ns (according to the standard mode I²C bus specification), before the SCL line is released.







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PIC18(L)F2X/4XK22





FIGURE 28-21: PIC18LF2X/4XK22 MAXIMUM IDD: RC_RUN LF-INTOSC 31 kHz



PIC18(L)F2X/4XK22





FIGURE 28-73: PIC18LF2X/4XK22 MAXIMUM IDD: SEC_RUN 32.768 kHz



44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN or VQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	MILLIMETERS			
Dimension	MIN	NOM	MAX	
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	X2			6.60
Optional Center Pad Length	Y2			6.60
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.85
Contact Pad to Contact Pad (X40)	G1	0.30		
Contact Pad to Center Pad (X44)	G2	0.28		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing No. C04-2103C